



## REVISION HISTORY

ECO	REV	DESCRIPTION	APP. ENG.	DATE
-	2	PRODUCTION	LEO C.	10-11-11

## NOTES: UNLESS OTHERWISE SPECIFIED

1. WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC-A-610.
2. ASSEMBLY PROCESS SHALL INCLUDE: REFLOW SOLDER TOP SIDE SMD. MAXIMUM SOLDER TEMPERATURE IS 240 DEG CELSIUS.
3. PARTS TO OMIT WILL BE SPECIFIED ON THE BILL OF MATERIALS. LOCATIONS OF OMITTED PARTS SHALL BE FREE OF SOLDER. MASK THE SOLDER STENCIL WHERE SMT PARTS ARE OMITTED.
4. INSTALL SHUNTS AS SHOWN ON ASSY DRAWING.
5. DEPANELIZE BOARDS AFTER ASSEMBLY AND ROUTE-OUT THE BREAKOUT TABS ON FOUR SIDES OF THE BOARD EDGE.
6. DO NOT APPLY ANY KIND OF ASSEMBLY STAMP OR QA STAMP TO ANY BOARD.
7. INSTALL LED1-LED5 AS SHOWN BELOW:



## APPROVALS

PCB DES. KIM T.

APP ENG. LEO C.

SCALE = NONE



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TITLE: TOP ASSEMBLY DRAWING

VOLTAGE AND TEMPERATURE MONITOR

SIZE N/A IC NO. LTC2995IUD  
DEMO CIRCUIT 1871A

REV.  
2

FILENAME: DC1871A-2.PCB

SHT 1 OF 2